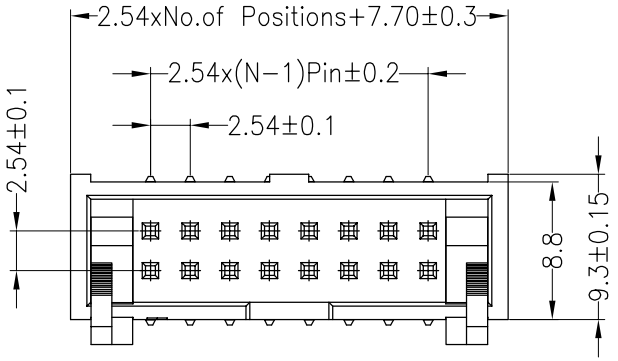
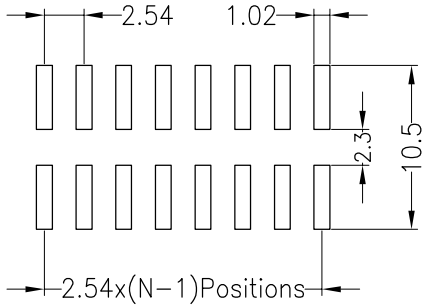
HSF RoHS

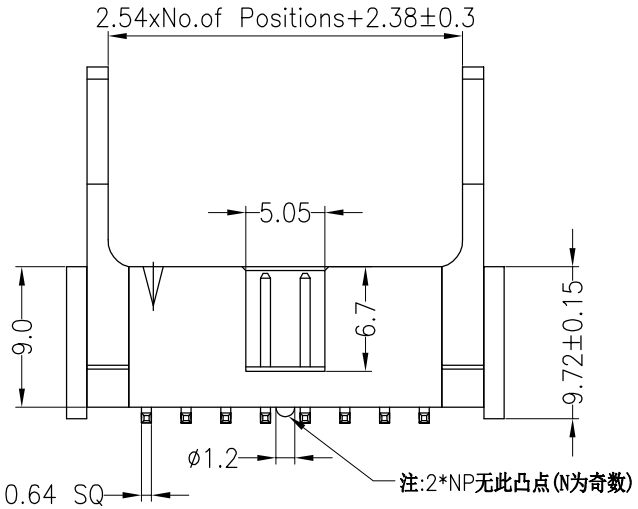
SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

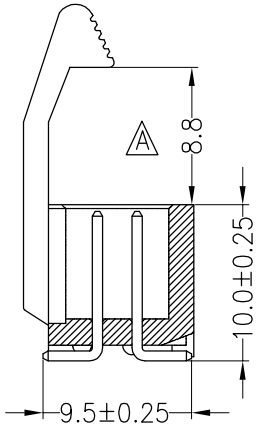
Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)



Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)







Ordering Information

3214 XX M XX X B K00 X 0X

- No.of Pins: 8--64
- Contact Plating: G0:Gold Flash; G1:1U" Gold; G2:1.5U" Gold; G3:2U" Gold; G4:3U" Gold; G5:5U" Gold; S0:Gold Flash/Tin; SN:Tin
- Insulator Material Option: C=BK−PA6T; D=BK−PA46; E=BK−PA9T; F=BK−LCP
- Packing: 0=PE Bag; A=Tray; T=Tube; P=Tube+Cap

REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A1	2018.10.12	"A" 尺寸原8.18变更为8.8	
A0	2014.05.26	NEW DRAWING	

OPERATION		DRAW	Liu Miao	18.10.12	SCALE	FIT
X.X	±0.30				UNIT	mm
X.XX	±0.20	CHECK			SIZE	A4
X.XXX	±0.10				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	
DIM	TOL					

WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	3214XXMXXXBK00X0X
TITLE:	2.54mm SMT 带金属钩简牛